# Product Change Notification

The information below reflects a change that is being implemented.

Notice Date: 10/29/2007

Product Category: 24xxx

Notification Subject: CCB#782.01-782.02: QUALIFICATION OF 24xxx1025 PRODUCT WITH HS231 DIE ATTACH FILM IN 8L SOIJ, .208” (CCB#782.01) AND HS231 DIE ATTACH FILM/ GE800 MOLD COMPOUND IN 8L PDIP, .300” (CCB#782.02) WITH SLIGHT CHANGES IN TOP DIE/SPACER DIE THICKNESS AT NSEB.

Notification Body:

Microchip Part#s Affected:
24AA1025
24LC1025
24FC1025

Description of Change:
CHANGE IN BOM AS WELL AS TOP DIE AND/OR SPACER DIE THICKNESS

8L SOIJ (CCB# 782.01):

Pre change:
Die Attach Film: 2200D
Top Die Thickness (mils): 11
Spacer Die Thickness (mils): 6

Post change:
Die Attach Film: HS231
Top Die Thickness (mils): 8
Spacer Die Thickness (mils): 8

8L PDIP (CCB# 782.02):

Pre change:
Die Attach Film: 2200D
Mold Compound: EME6600CS
Top Die Thickness (mils): 15

Post change:
Die Attach Film: HS231
Mold Compound: GE800
Top Die Thickness (mils): 8

Impacts to Data Sheet:
NONE

Reason for Change:
TO IMPROVE MANUFACTURABILITY

Estimated Change Implementation Date(s):
NOVEMBER 30, 2007

Markings to Distinguish Revised From Unrevised Devices:
(e.g.: Date Code, Device Marking, Ship Container Marking)
TRACEBILITY CODE